



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application

Inventor(s): Nguyen

Appln. No.: 10/795,950

Confirm. No.: 1419

Filed: March 8, 2004

Title: Multilayer Copper Structure for Improving
Adhesion Property

PATENT APPLICATION

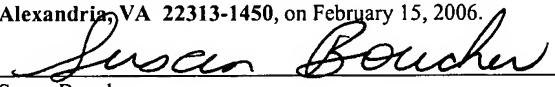
Art Unit: 2823

Examiner: Jarrett J. Stark

Customer No. 23910

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited in the United States Postal Service with sufficient postage as first class mail in an envelope addressed to **Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450**, on February 15, 2006.


Susan Boucher (Signature)
Susan Boucher
Signature Date: February 15, 2006

REPLY TO OFFICE ACTION UNDER 37 C.F.R. § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Communication of December 13, 2005, please amend the above-identified application as follows:

Remarks/Arguments begin on page 2 of this paper.